



喬訊電子工業股份有限公司  
 CHYAO SHIUNN ELECTRONIC INDUSTRIAL LTD.  
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Type Document	Product Specification	Revised /Edition	I
Date Issued	2007/10/31	Data Revised	2013/11/27
Subject : JS-ID0800-XX JS-ID0801H-XX/(NM)/(G) JS-ID0801V-XX/(NM)/(G) Pitch 0.8mm SMT Series Wire to Board Insulation Displacement Connector			Issued By: Engineering Dept.

*This specification is referred to 0.80mm SMT series  
 Wire to Board Insulation Displacement connector.  
 本規格書內容係提供 0.80 mm SMT 系列產品相關參考，  
 其用途為電線端相接於電路板端之絕緣體刺破型連接器*

## -INDEX-

- 1.0 Product Name/Part Number & Drawing Number.(產品名稱 / 產品型號及圖面型號)
- 2.0 Construction/Dimensions/Material & Surface Finish.(材質以及表面鍍層)
- 3.0 Characteristic.(產品特性)
- 4.0 Specimen.(樣本圖示)
- 5.0 Applicable Standards.(適用規範)
- 6.0 Mechanical Performance.(機械性能)
- 7.0 Electrical Performance.(電氣性能)
- 8.0 Environmental Performance.(環境性能)
- 9.0 Insertion Force (I.F.) & Withdrawal Force (W.F.) for user reference(插入力與拔出力參考規格)
- 10.0 Caution (注意事項)
- 11.0 Remark (備註).

REV. (版次)	Revision Record (改版變更原因)	Date(日期)	EC No
E	增加中文敘述 以及增加版次變更註記欄	2010/01/22	EC2010-01-032
F	修改Solder Tab材質，修改AWG #32 額定電流，修改迴焊耐溫，增加21,22 Pin	2010/12/13	EC2010-12-007
G	參照 JST 樣品實測值 修改 Insertion & Retention Force 插入力與拔出力規格值	2011/12/15	EC2011-12-007
H	增加產品使用注意事項	2012/02/09	EC2012-02-020
I	1.修訂 Solder Ability 附註 Tin Plated : 95% / Gold Plated : 75% 2.增訂(IPC/JEDEC J-STD-020D.1) 參考規範	2013/11/27	EC2013-11-027



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**1.0 Product Name/Part Number & Drawing Number(產品名稱 / 產品型號及圖面型號):**

Product Name(產品名稱)		Part Number(零件型號)	Drawing Number(圖面型號)
(IDC)Housing		JS-ID0800-XXXXXXXXNH	
Wafer	Straight	JS-ID0801V-XXXX / JS-ID0801V-XX(G) / JS-ID0801V-XX(NM)	
	Right Angle	JS-ID0801H-XXXX / JS-ID0801H-XX(G) / JS-ID0801H-XX(NM)	

Note: (xx) The number of the circuits

**2.0 Construction/Dimensions/Material & Surface Finish(材質以及表面鍍層):**

Part Name(零件名稱)		Material(材質)	Surface Finish(表面鍍層)
(IDC)Housing (電線端刺破型連接器)	Contacts (導體)	Copper Alloy	Gold or Tin-Plated
	Base (膠座)	Nylon 66+30%Glass Fiber (Non-Halogen 無鹵素)	UL 94V-0(Color : Nature)
		LCP	UL 94V-0(Color : Black)
Wafer (電路板端連接器)	Contacts (導體)	Copper Alloy	Gold / Tin / Matte-Tin Plated
	Solder Tab (固定片)	Brass	
	Base (膠座)	Nylon 9T	UL 94V-0

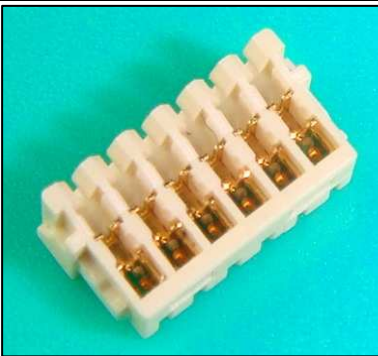
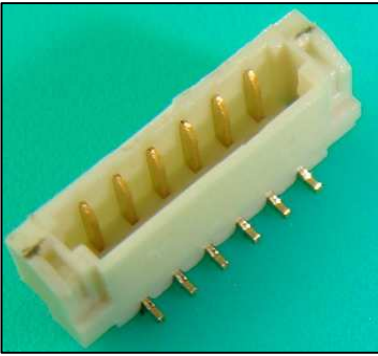
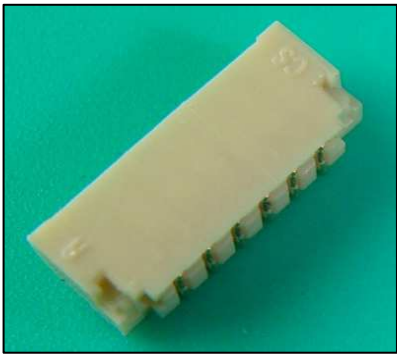
**3.0 Characteristic(產品特性):**

Item(項目)		Standard(標準規範)	
3.1	Rated Current 額定電流	0.7A AC/DC With AWG #32 is applied	
		0.2A AC/DC With AWG #36 is applied	
3.2	Rated Voltage 額定電壓	50 V DC	
3.3	Ambient Temperature Range 環境與操作溫度範圍	(操作使用溫度範圍) Operating Temp.: -25°C~+85°C Including 30°C Terminal Temperature Rise at rated Current , (包括定額電流內, 端子所產生 30°C 以下溫昇) (置存於環境當中溫度與濕度範圍) Non – Operating Temp. : -25°C~+85°C ; 90% R.H. Max	
		Conductor Construction Size:	
3.4	Applicable Wire 適用電線	AWG #32	AWG #36
		Insulation O.D. Ø0.39mm	Insulation O.D. Ø0.39mm
		電線絕緣材質外徑	電線絕緣材質外徑
3.5	Applicable Printed Circuit Board Layout 適用電路板佈局設計	3.5.1	SMT Layout: 0.80 ± 0.05 mm per Pitch 表面黏著焊錫點間距
		3.5.2	SMT Layout: 0.5X1.00±0.05 mm for Pin Post 導體焊錫點面積
		3.5.3	SMT Layout:1.20X1.70±0.05 mm for Solder Tab 固定片焊錫點面積



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**4.0 Specimen(樣本圖示) :**

Part Name / Part Number / Picture or Photograph 零件名稱 / 零件型號 / 樣本圖示			
(IDC)Housing  JS-ID0800-XXXXX  XXNH			
Wafer  Straight  JS-ID0801V-XXXX		Wafer  Right Angle  JS-ID801H-XXXX	

**5.0 Applicable Standards(適用規範):**

ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors.

電子連接器，所適用之 ANSI/EIA 364 ; EIA/ECA 364 測試規範

**6.0 Mechanical Performance(機械性能):**

Item(項目)	Test Condition(測試條件)	Requirement(規格)
6.1	Insertion & Withdrawal Force 嵌入力與拔出力  A socket with correctly terminated wires and a header shall be mated and unmated on the mating axis. Initial insertion and withdrawal forces and withdrawal force at 30 times shall be measured. (testing speed) : 1 to 5 mm/sec (EIA/ECA 364-13D) 將埋入電線之連接器膠座，以每秒 1 至 5mm 速率，與電路板端連接器連續進行 30 回嵌合與拔出往返測試，並量測首回與 30 回之後拔出力	Refer to 9.1 Table1. 參照第 9.1 項 表格 1



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Item(項目)		Test Condition(測試條件)	Requirement(規格)
6.2	Wire Retention Force 電線脫離端子之拔出力	Pulling load shall be applied to correctly terminated wire in parallel and perpendicular directions. The load to pull the wire out of the socket or break the wire shall be measured . (testing speed : 1 to 5 mm/Sec) 先以電線末端採正確方向(電線軸向與端子軸向平行)埋入嵌有端子的膠座，而後以每秒 1 至 5 mm/Sec 速率，測試電線脫離膠座或者未脫離膠座電線即斷裂，並量測其最終拔出力	垂直於電線軸方向之拔出力 <b>Perpendicular Direction</b> <b>AWG#36</b> <b>0.15kgf(Min.)</b> 最小容許值
		平行於電線軸方向之拔出力 <b>Parallel Direction</b> <b>AWG#36</b> <b>0.40kgf(Min.)</b> 最小容許值	
6.3	Pin Retention Force( in Base ) Pin 針與膠座之間拔出力	The contact mounted in a wafer shall be pulled in the axial direction . The load to pull the contact out of the wafer shall be measured. (Testing speed : 25mm/minute) (EIA 364-29C) 以每分鐘 25mm 速率將電路板端連接器當中 Pin 針，依原先 Pin 針嵌入膠座之軸向作拔出力測試	單一接觸點 Per Contact <b>0.26kgf(Min.)</b> 最小容許值

7.0 Electrical Performance(電氣性能) :

Item(項目)		Test Condition(測試條件)	Requirement(規格)
7.1	(Low –Signal Level) Contact Resistance (低階信號) 接觸阻抗	A maximum voltage of 20mV and a maximum current of 1mA(DC) are applied to the mate connector. 對組合狀態下連接器，於其兩端施以最大電壓 20mV 以及直流電 1mA(DC) (EIA/ECA 364-23C) ( Does not include wire resistance 不包含電線阻抗 )	Contact Resistance: <b>20 milliohms Max.</b> 最大容許值. 20m 歐姆
7.2	Insulation Resistance 絕緣阻抗	Apply 250V D/C for 1 minute between adjacent contacts to measure the insulation resistance. 對相鄰兩接觸導體，於一分鐘時間內施予 250V D/C 電壓，並量測其間絕緣阻抗值 (EIA 364-21C)	Insulation Resistance: <b>Initial 100 Megohms Min</b> 最初容許值. 100 M 歐姆



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
7.3 Withstanding Voltage 耐電壓	Apply <b>200V A/C (rms)</b> for 1 minute and the leakage current shall not exceed <b>0.5mA</b> to the adjacent terminal and ground of the mate connectors. (EIA 364-20C) 對組合狀態下連接器，於其相鄰兩導體末端各施以電壓 <b>200V A/C(實效值)</b> 時間 1 分鐘,且漏電流必須小於 <b>0.5mA(毫安培)</b>	No breakdown or flashover. 無損毀或者產生火花

8.0 Environmental Performance(環境性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.1 Durability 耐久性	Mate Connectors up <b>30</b> Cycles at a Maximun rate of <b>10</b> cycles Per minute prior to environmental test (EIA/ECA 364-09C ) 以組合狀態下連接器且未經環境測試，依每分鐘內進行10次嵌入與拔出之最大速率，連續 <b>30</b> 次嵌入與拔出往返測試	(After the test) Contact resistance : 經耐久性試驗後接觸阻抗： <b>40 mΩ Max</b>
8.2 Temperature Rise Via Current Cycling) 溫昇 (經由電流循環操作)	Mate connector . measure the temperature rise of contact when the maximum rated current is passed 以組合狀態下連接器，通過最大容許電流 量測其導體溫度上昇值 (EIA 364-70B Conditions 1 . Method 1)	Mate connectors <b>Temperature Rise:</b> <b>+30°C/Max.</b> 組合狀態下之連接器溫度 上昇最大容許值+30°C
8.3 Vibration 耐振動	A mated connector shall be mounted on a printed Circuit board and subjected to a vibration test of the following conditions. During the test, test current continuity shall be checked. After the test, contact resistance shall be measured. 以組合狀態下連接器焊接於電路板作為試驗樣品,依照隨附如下規格要求,進行耐振動試驗，試驗過程中確認是否產生不連續電流(斷電)現象，並於試驗過後量測其接觸阻抗。 (EIA/ECA 364-28E-Condition I) Frequency(頻率) : 10~55~10 Hz/minute. Amplitude (振幅) : 1.5 mm P-P Direction (方向) :1. Axis of up and down.上下軸向(Y 軸) 2. Axis of right the left. 左右軸向(X 軸) 3. Axis of front and back.前後軸向(Z 軸) Period(週期) : 2 hours for each direction. (每一個軸向持續 2 小時)	Initial Contact Resistance : <b>20 milliohms Max.</b> 接觸阻抗最初容許值: <b>20m 歐姆</b> (After the test) Contact Resistance: <b>40 milliohms Max.</b> 經耐振動試驗後接觸阻抗： 最大容許值 <b>40m 歐姆</b>
		No discontinuity current is longer than 1 microsecond. 電流中斷現象， 時間不可多於1微秒



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.4 Humidity (Steady State) 恆溫恆濕	<p>A mated connector shall be placed in a humidity chamber of the following conditions. After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>以組合狀態下連接器放置於恆定溫度與濕度的空間，依照隨附如下規格要求，進行恆溫恆濕試驗，並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>(EIA 364-31B Conditions III . Method A)</p> <p>Temperature(溫度) : 40±2°C.</p> <p>Relative Humidity(相對濕度) : 90%~95% (RH).</p> <p>Period(週期) : 96 hours continuously. (持續 96 小時)</p>	<p>(After the test)</p> <p>Contact Resistance: <b>40 milliohms Max.</b> 經恆溫恆濕試驗後接觸阻抗： 最大容許值. 40m 歐姆</p> <hr/> <p>(After the test)</p> <p>Insulation Resistance : <b>100 Megohms Min.</b> 經恆溫恆濕試驗後絕緣阻抗： 最小容許值. 100 M 歐姆</p> <hr/> <p>經恆溫恆濕試驗後耐電壓</p> <p>(After the test)</p> <p>Withstanding Voltage : <b>100V AC</b></p>
8.5 Thermal Shock 冷熱衝擊	<p>A mated connector shall be subjected to a thermal shock test of the following conditions. After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行冷熱衝擊試驗，並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>(EIA/ECA 364-32D Conditions I . Method A)</p> <p>One Cycle Consists Of:</p> <p><b>-55 +0/-3°C for 30 minutes. → Room Temp.5 minutes</b>  <b>85+3/-0°C for 30 minutes. → Room Temp.5 minutes</b></p> <p>Total Cycles: 5 Cycles.</p> <p>以-55+0/-3°C溫度持續 30 分鐘，經室溫 5 分鐘，而後再以 85+3/-0°C溫度持續 30 分鐘，再經室溫 5 分鐘，構成一次冷熱循環，總計循環次數 5 次。</p>	<p>Same as paragraph 8.4 同 8.4 章節</p>



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.6 Heat Aging 高溫老化試驗	A mated connector shall be placed in a heat oven of the following conditions. After the test, contact resistance shall be measured. 以組合狀態下連接器放置於加熱烤箱當中, 依照隨附如下規格要求, 進行高溫老化試驗, 並於試驗過後量測其接觸阻抗。(EIA 364-17B Conditions III . Method A) Temperature(溫度): 85±2°C. Period(週期): 96 hours continuously.(持續 96 小時)	Initial Contact Resistance : 20 milliohms Max. 接觸阻抗最初容許值:20m 歐姆 (After the test) Contact Resistance : 40 milliohms Max. . 經高溫老化試驗後接觸阻抗 : 最大容許值. 40m 歐姆
8.7 Salt Spray 鹽水噴霧	A mated connector shall be subjected to a Salt Spray test of the following conditions. After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance. 以組合狀態下連接器作為試驗樣品, 依照隨附如下規格要求, 進行鹽水噴霧試驗 , 試驗過後將樣品用清水沖洗並經過自然風乾 , 而後量測其接觸阻抗。(EIA 364-26B Conditions B) Density(鹽水密度): 5 % in weight. Temperature(溫度): 35±2°C. Period(週期): 48 hours	Initial Contact Resistance : 20 milliohms Max. 接觸阻抗最初容許值:20m 歐姆 (After the test) Contact Resistance: 40 milliohms Max. 經鹽水噴霧試驗後接觸阻抗 : 最大容許值. 40m 歐姆
8.8 Solder Ability 焊錫性	Fluxed soldering section of header shall be dipped in solder of the following conditions. 將連接器 pin 針基板嵌入端, 接觸熱溶狀錫料, 依照隨附如下規格要求, 進行焊錫性試驗 (EIA 364-52B) Solder Temperature (焊錫溫度): 245 ± 5°C. Immersion Period (沉浸週期): 3±0.5 Seconds (操作方式): 零件焊錫位置, 距離導體以及固定片末端 0.5mm Method : 0.5mm from contact tip and solder tab tip	Solder entirely (Tin Plated : 95% / Gold Plated : 75%) of immersed area must show no voids or pinholes. 焊料覆蓋面積必須達到 (鍍錫 95% / 鍍金 75%), 而且不能產生氣孔或空隙

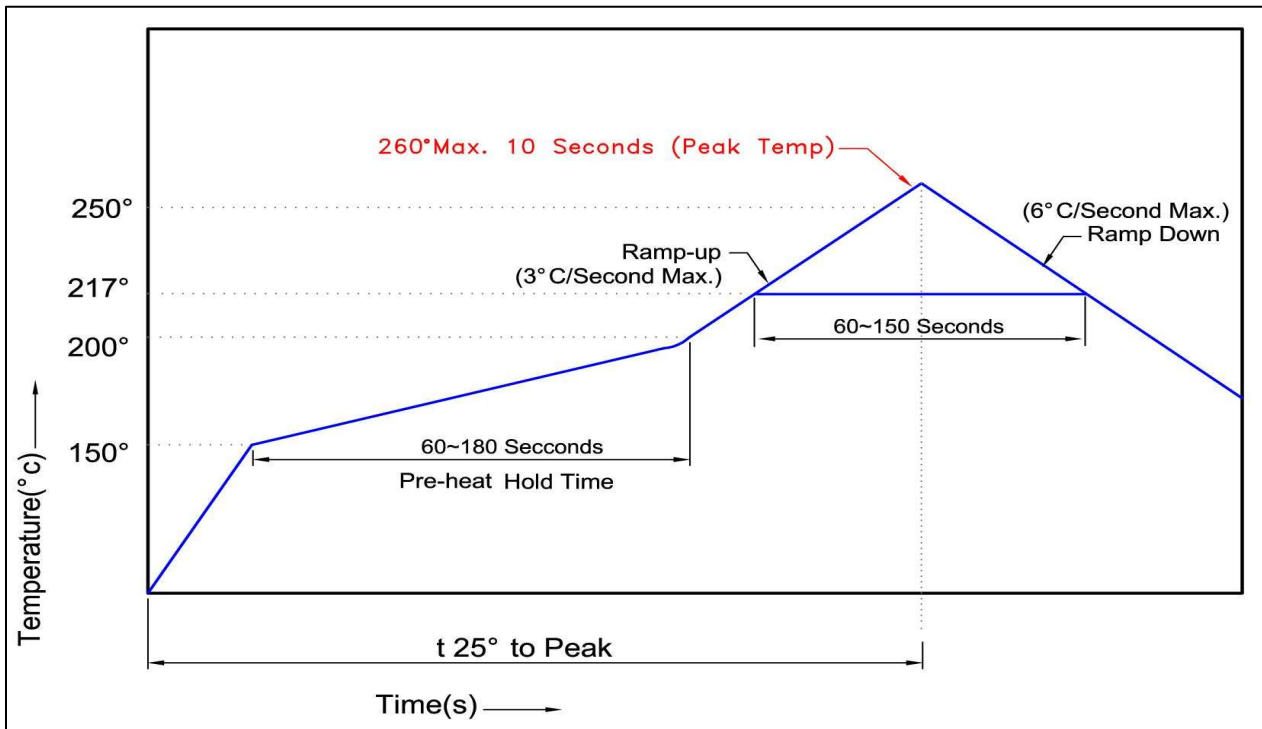


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8.9 Resistance To Soldering Heat 焊錫耐熱性	By reflow soldering 迴焊適用溫度範圍 : Refer to Temperature Profile 請參考 8.9.1 溫度曲線圖 (IPC/JEDEC J-STD-020D.1) By soldering iron 手工烙鐵焊錫適用溫度範圍 : 350 ± 5°C 3±0.5 Seconds. (操作方式) : 零件焊錫位置 , 距離導體以及固定片末端 0.5mm Method : 0.5mm from contact tip and solder tab tip (EIA/ECA 364-56C Procedure 3. Conditions A)	No deformation or damage. 不可有變形或損壞

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試依照客戶需求

8.9.1 Temperature Profile(溫度曲線圖) :







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<b>Type Document</b>	<b>Product Specification</b>	<b>Revised /Edition</b>	<b>I</b>
<b>Date Issued</b>	<b>2007/10/31</b>	<b>Data Revised</b>	<b>2013/11/27</b>
<b>Subject : JS-ID0800-XX JS-ID0801H-XX/(NM)/(G) JS-ID0801V-XX/(NM)/(G)</b> <b>Pitch 0.8mm SMT Series Wire to Board Insulation Displacement Connector</b>			<b>Issued By:</b> <b>Engineering Dept.</b>

9.0 Tables & Attachments

9.1 Table 1. Insertion Force (I.F.) & Withdrawal Force (W.F.) for user reference:

No. Of Circuits 極數	AT INITIAL 首次嵌入與拔出(初始值)		AT 30 <sup>TH</sup> 30 次嵌入與拔出之後	No. Of Circuits 極數	AT INITIAL 首次嵌入與拔出(初始值)		AT 30 <sup>TH</sup> 30 次嵌入與拔出之後
	I.F. (MAX) 嵌入力	W.F. (MIN) 拔出力	W.F. (MIN) 拔出力		I.F. (MAX) 嵌入力	W.F. (MIN) 拔出力	W.F. (MIN) 拔出力
	02	1.20	0.17		0.05	13	2.35
03	1.33	0.20	0.07	14	2.45	0.53	0.32
04	1.43	0.23	0.09	15	2.55	0.56	0.34
05	1.53	0.26	0.11	16	2.65	0.60	0.36
06	1.63	0.29	0.14	17	2.75	0.63	0.39
07	1.73	0.32	0.16	18	2.85	0.67	0.41
08	1.83	0.35	0.18	19	2.95	0.70	0.43
09	1.93	0.39	0.20	20	3.05	0.73	0.46
10	2.03	0.42	0.23	21	3.10	0.76	0.48
11	2.14	0.44	0.25	22	3.20	0.79	0.50
12	2.24	0.46	0.27				

Unit : Kg/f

**10.0 Caution (注意事項) :** Parts are made of hydrophilic Polyamide 9T and apt to absorb moisture. Once the vacuum-packing unpacked, please keep parts in the environment of **temperature < 30°C/ humidity < 60% RH**, and send to re-flowing **within 72 hours** to prevent parts blistered or deformed during soldering.  
 PA9T塑料因具親水之特性，故採用真空包裝以減少吸濕受潮。真空包裝經拆封應**避免曝露於溫度高於30°C，濕度高於 60% RH的環境中，並在拆封72 小時內全數使用完畢**，以防止後續迴焊製程產生起泡變形現象。

**11.Remark(備註) :** Any change or revision for the product specification will not be announced in advance.

Please contact our sales representative for the latest information.

有關規格書內容經變更或改版，如未能夠及時發佈與通知，煩請連絡我司業務人員以提供產品最新資訊

**Reviewed:** J.M.Chang **Approved:** Peter Chang **Verified:** Indiana Huang



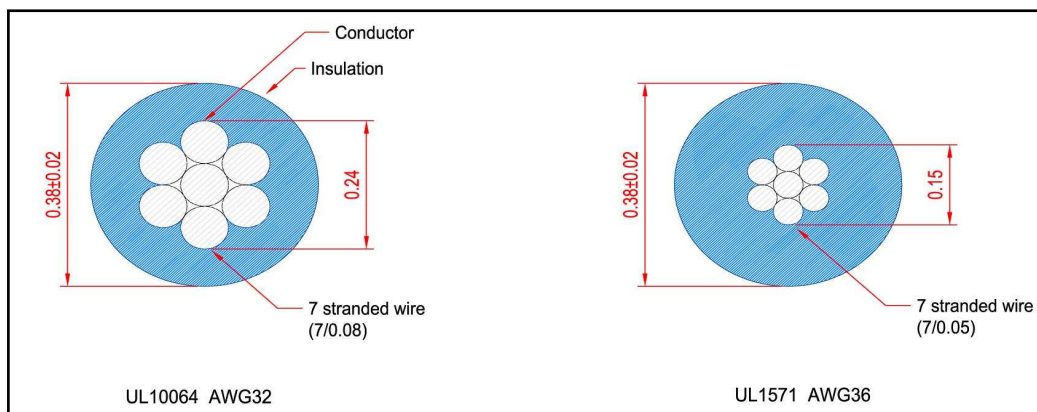
<b>Date Issued</b>	<b>2012/7/20</b>	<b>Revised /Edition</b>	<b>B</b>
<b>Title of Document</b>	<b>HANDLING MANUAL</b>		<b>Issued By: Engineering Dept.</b>
<b>Title Subject</b>	<b>Pitch 0.80mm (IDC) Wire to Board Connector JS-ID0800-XX ; JS-ID0801H-XX ; JS-ID0801V-XX</b>		

*This manual describes important and required points of handling about connector . Be sure to read this manual thoroughly before using connector.*

此操作手冊係說明連接器使用時必須注意的重點事項，  
務必詳加閱讀內容之後，再行使用本產品

**1. Applicable Wire 適用電線規格：**

Item	Rated value(額定標準)	
Wire size 電線型號	(UL 10064) AWG #32	(UL 1571) AWG #36
Wire insulation outer dia. 電線絕緣被覆層外徑	$\varnothing 0.38 \pm 0.02 \text{mm}$	$\varnothing 0.38 \pm 0.02 \text{mm}$
Conductor spec. 導體規格	Tin-plated copper alloy wire 銅合金鍍錫線	
	(7/0.08) 7 條芯線/單一芯線外徑 0.08mm	(7/0.05) 7 條芯線/單一芯線外徑 0.05mm



**2. Terminating Operation Precautions 壓接作業須知：**

※ 芯線必須完全壓入端子U槽，否則會造成電氣導通失效

The terminal should be pressed into the U slot completely or the electronic conduct function would be invalid. (See Figure 2.1)

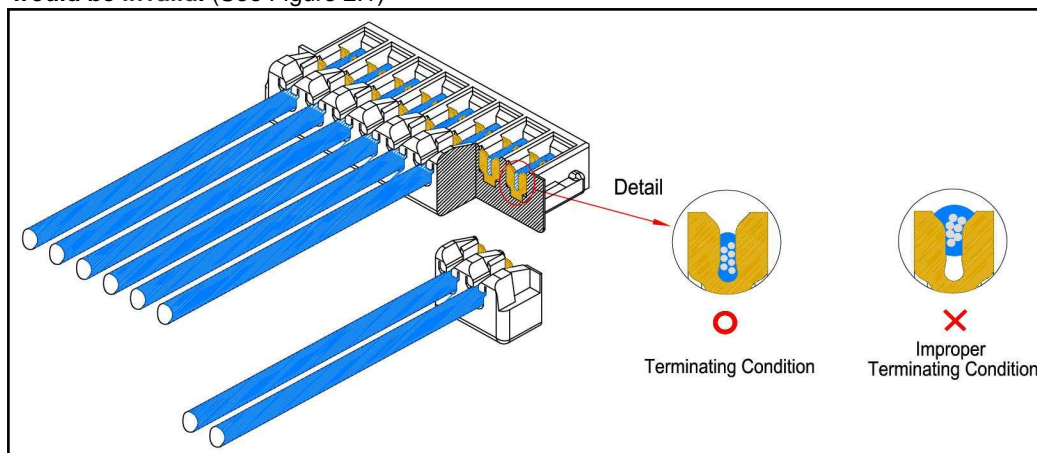


Figure 2.1



<b>Date Issued</b>	<b>2012/7/20</b>	<b>Revised /Edition</b>	<b>B</b>
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<b>Title Subject</b>	<b>Pitch 0.80mm (IDC) Wire to Board Connector JS-ID0800-XX ; JS-ID0801H-XX ; JS-ID0801V-XX</b>		

※ 電線壓接長度過短或者過長，將會影響機械性能  
The mechanical function might be affected, while the length of the wire is protruded too long or too short. (See Figure 2.2)

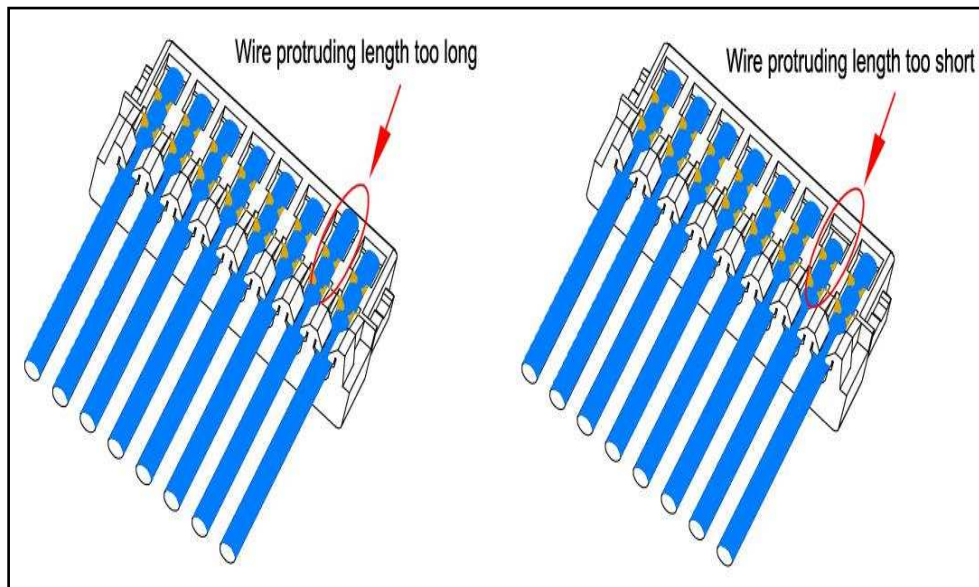


Figure 2.2

※ 電線芯線外露或者電線壓接過於偏離中心位置，將會影響電氣性能  
The electronic function might be affected, while the conductor is appeared or deflected of the center location. (See Figure 2.3)

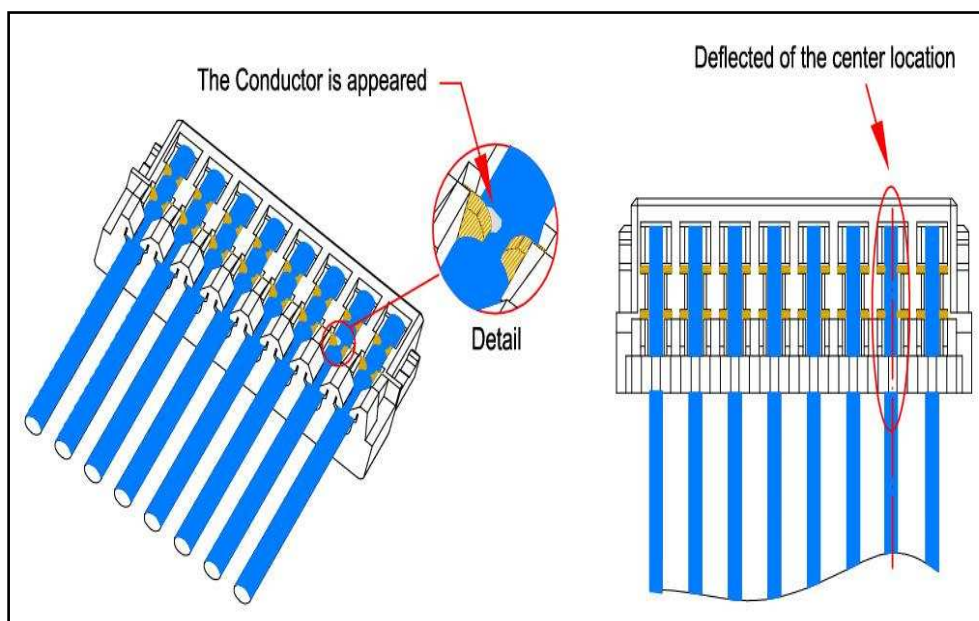


Figure 2.3



<b>Date Issued</b>	<b>2012/7/20</b>	<b>Revised /Edition</b>	<b>B</b>
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<b>Title Subject</b>	<b>Pitch 0.80mm (IDC) Wire to Board Connector JS-ID0800-XX ; JS-ID0801H-XX ; JS-ID0801V-XX</b>		

### 3.0 Handling Precautions for SMT 使用表面黏著須知：

#### 3.1 Reflow Soldering Method 迴焊使用方法：

Soldering should be conducted at the temperature below the temperature profile shown in product Specification as item of "Resistance to soldering heat"

迴焊所適用溫度條件，參照規格書“焊錫耐熱性”項目中所示溫度曲線圖。

Though recommended reflow temperature condition varies depending on solder paste to be used, evaluate and find adequate condition before production.

迴焊建議溫度僅為參考，溫度條件的變化亦取決於錫膏的使用，視實際使用需求而作調整。

Depending on the soldering condition, solder and flux wicking may occur on this connector.

Check no problem in customer soldering condition before the use.

錫膏毛細現象，攸關迴焊條件良窳，有可能造成連接器使用時溢錫、爬錫之發生。

迴焊所需具備之條件，應先確認無誤之後，再行使用本產品

Considering Handling of this connector in mating operation, tenacious heat-resistant resin is used for this connector. But 'Blister' may generate on the outer surface of the housing during the process of reflow soldering, depending on the condition of moisture absorption of the housing and the condition of reflow soldering. However, because 'blister' is not caused by decomposition of resin, it does not affect the performances of the connector.

連接器所採用具剛性且耐高溫之塑膠，經迴焊製程可能會在連接器表面產生氣泡，其生成的原因源自於塑膠過度吸濕以及迴焊製程條件優劣，然而氣泡並不會對於塑膠產生侵蝕的作用，而且就連接器組裝使用功能性而言並不影響。

There is no influence in the product performance though discoloration might be generated in the resin according to reflow condition.

迴焊製程亦可能引起塑膠色澤變化，但不影響產品功能。

#### 3.2 About whisker growth prevention for this product 關於避免錐鬚的生成

The Lead-Free plating of this product has been performed by re-flow matte-tin or gold plating which ensures maximum effectiveness for retarding whisker growth. It fully comply with JEDEC-JP002-(Current Tin-Whiskers Theory and Mitigation Practices Guideline.)

此產品經採用無鉛鍍錫或鍍金施行於迴焊製程，已確認其對於延緩錐鬚生長可發揮最大效用。此方式完全符合 JEDEC-JP002 規範（當前通用的錐鬚理論和緩解實例指導方針）。

#### 3.3 Connector Placement 連接器定位

Machine placement of the connector is recommended due to the inherent difficulty of manually placing fine-pitch connectors. The top surface of the connector housing has a flat area in the center to facilitate vacuum pick-up and handling. To avoid damage, the connectors should be picked up directly out of the embossed-tape packaging by the pick-up device. The placement machine is used to position the connectors to minimize the possibilities of damage that could result from improper handling.

細距連接器經由手工置件定位極富難度，建議以機械方式置件定位取代，機械方式置件定位，可降低因操作不當而導致連接器損壞的情形發生。連接器表面平坦處且位於整體中心位置，較易於真空取件作業。真空取件應以垂直起降方式，將零件由包裝載帶取出，並避免損壞連接器。

Placement of the connectors may be done by hand; however, extreme caution must be used when handling connectors to prevent deformation and contamination of the solder tines and hold-downs.

某些情況下可能以手工置件定位，尤特別謹慎避免連接器沾污、以及過度施力損壞連接器金屬導體末端焊錫區域。

#### 3.4 Coplanarity 金屬導體與焊錫區域共面度：

Optimally, the connector contact solder tines should be centered on the PC board Pads. however, misregistration is permissible for some performance classifications.(See Figure 3.4)

連接器金屬導體安放之最佳位置應座落於印刷電路板各相對應腳位之焊錫區域之中心線，然而對於有些效能特性之分類，可允許對位落差。



<b>Date Issued</b>	<b>2012/7/20</b>	<b>Revised /Edition</b>	<b>B</b>
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<b>Title Subject</b>	<b>Pitch 0.80mm (IDC) Wire to Board Connector JS-ID0800-XX ; JS-ID0801H-XX ; JS-ID0801V-XX</b>		

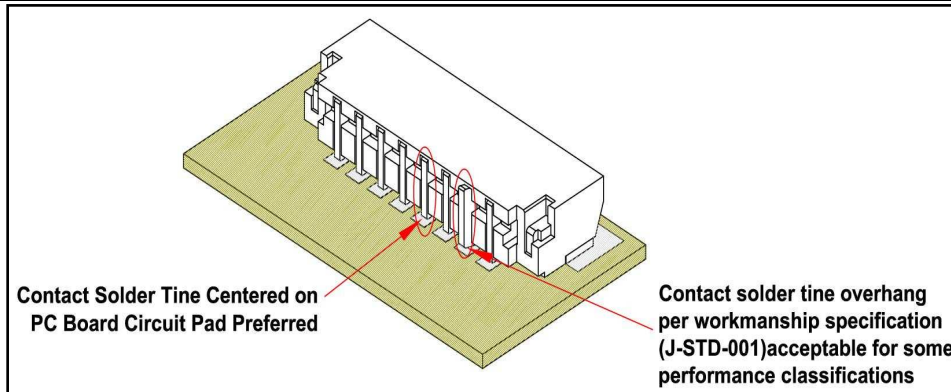


Figure 3.4

### 3.5 Solder Iron Method 手焊使用方法：

When soldering or re-soldering connector on PC board , below the temperature shown in product Specification as item of “ Resistance to soldering heat “

電路板上連接器使用手工焊錫或者是重焊 所適用溫度條件，參照規格書“焊錫耐熱性”項目中所建議溫度。

Do not apply external force by pressing soldering iron tip on contact solder tail part.

切勿以過度的力量，將烙鐵尖端重壓導體末端焊錫區域。

If done, dismount and exchange connector. Do not reuse dismantled connector.

如以手焊方式卸除連接器應將其更換，切勿重覆使用已卸除之連接器。

### 4.0 Recommended Insertion 連接器嵌入組合建議使用方式

4.1 This connector is designed for polarizing. Please be careful on the direction of the housing insertion. (see figure 4.1)

此款連接器設計具有防止逆向嵌合之功能，請務必於嵌入線端連接器的同時確認其方向正確與否。

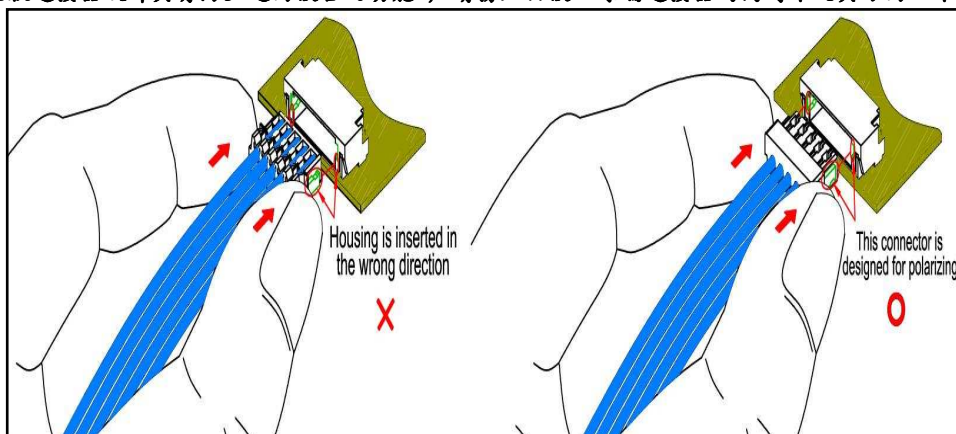


figure 4.1.

4.2 Make allowance so that the power of more than the tension by bending the Wire is not applied to the connector when handling the wire. In mating operation, mate a connector with holding wires in a bundle on the same axis to mating axis. (see figure 4.2)

嵌入時，請保持施力平均，如此一來在線材折彎時產生的力量就不至於會影響到連接器。連接器嵌入的同時，線材需先以手握成束並與線端連接器在同軸方向。



<b>Date Issued</b>	<b>2012/7/20</b>	<b>Revised /Edition</b>	<b>B</b>
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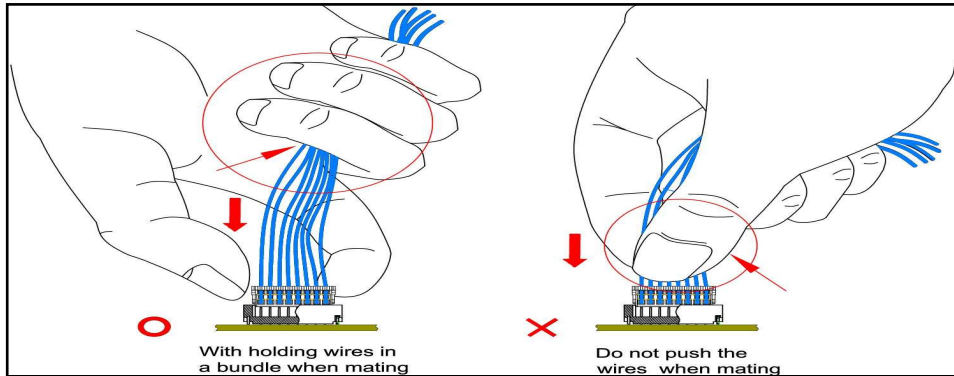


figure 4.2

- 4.3 It causes deformation due to the housing come into contact with the base contact when the housing inserted into the wafer with leaning. Housing shall be mated without twist or wrench. In case twist or wrench should occur, it should be within 3 deg. (see figure 4.3)

當線端連接器欲嵌入板端連接器時，插入時若過於傾斜易造成連接器接觸面的變形。線端連接器以扭轉之角度嵌入組合，其所能容許的角度約在3度以內。

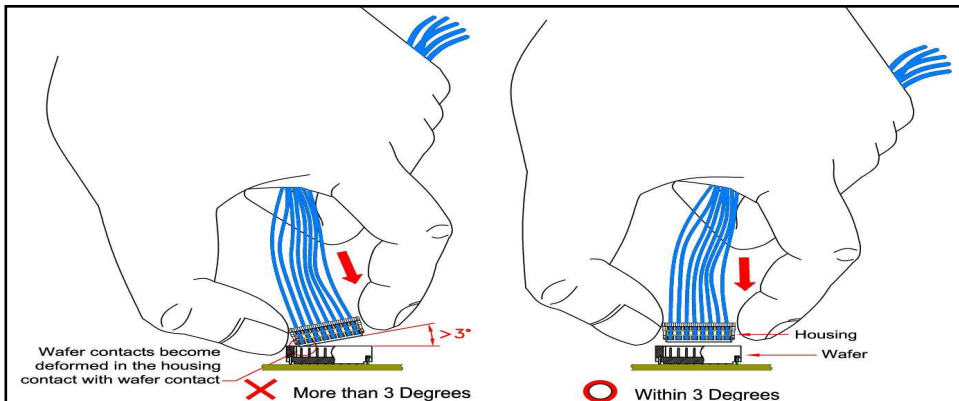


figure 4.3

- 4.4 After mating operation, check that there is no clearance between wafer and housing , because such clearance may lead discontinuity of connector. (see figure 4.4)

嵌入組裝之後須確認線端連接器與板端連接器之間沒有存在縫隙，縫隙可能使電氣導通失效。

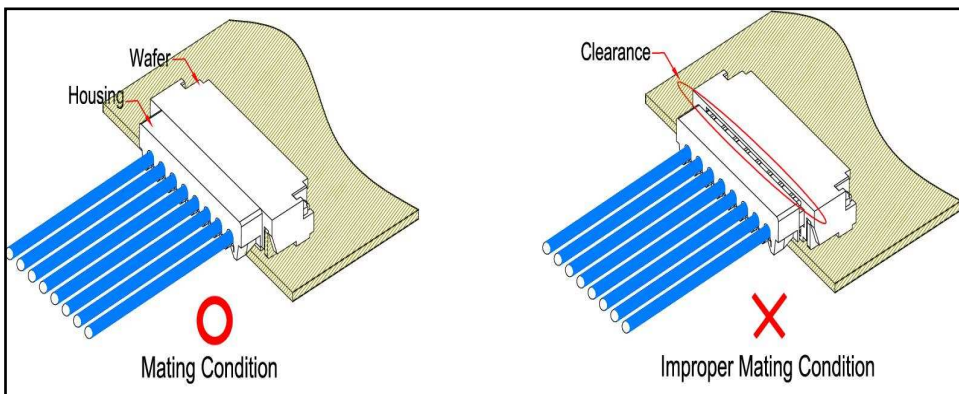


figure 4.4



<b>Date Issued</b>	<b>2012/7/20</b>	<b>Revised /Edition</b>	<b>B</b>
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## 5.0 Recommended removal 卸除連接器建議使用方式

5.1 Please hold all wires equally to prevent excessive force on certain wires. excessive force could lead to damage. (see figure 5.1)

請將握持電線的力量均勻分佈於每條電線，避免過度施力於某幾條電線，施力過度可能導致損壞。

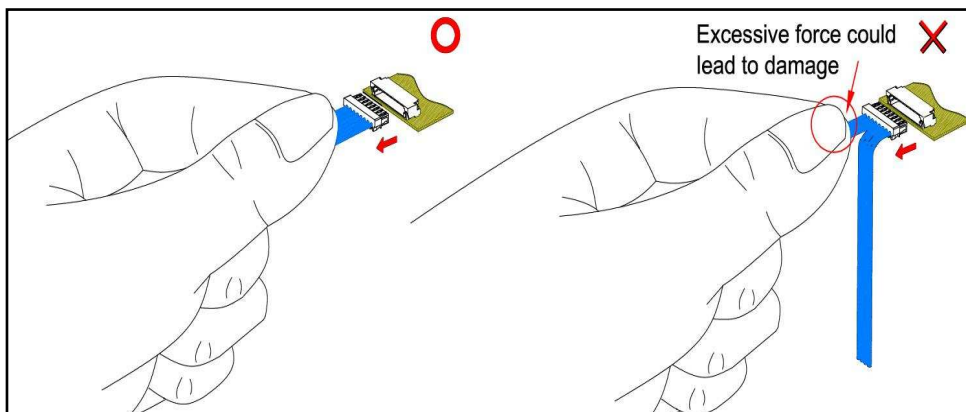


figure 5.1

5.2 Hold wires in a bundle and unmate housing from wafer on the same axis. At this time, conduct operation within 20 degrees to mating axis. 在拔除連接器時，務必先握住線材成束後，並與連接器保持同軸，線材折彎角度要在同軸角度的 20 度內進行。(see figure 5.2)

Do not unmate Housing forcibly with prying more than 20 degrees, because such handling may cause breakage of connector. 切勿在拔除連接器時，試圖以超越 20 度以上拔出幅度強行拔出連接器，可能導致連接器破損。(see figure 5.2)

When using AWG #36 wire, as the strength of wire itself is low, careful operation is required so that force may be equally applied to all wires. 36 號電線本身抗拉強度低，操作使用當時須格外注意，施力適當與否可能影響整組線材

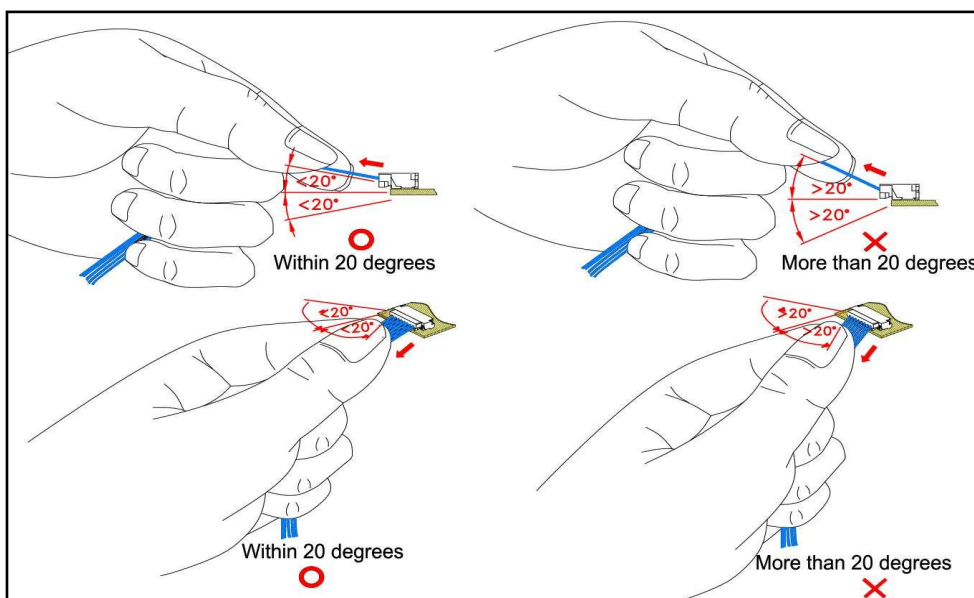


figure 5.2



<b>Date Issued</b>	<b>2012/7/20</b>	<b>Revised /Edition</b>	<b>B</b>
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## 6.0 Handling of wire after mounting connector on PC Board:

連接器於電路板裝載完成，後續線材配置方式

- 6.1 Conduct wire handling carefully so that tension more than **1N** may not be applied per connector and one wire. Provide space above connector in order to form wire by bending and do not apply tension to connector. (see figure 6.1)

電線承受過度的彎折會引起緊縮的張力，而連接器所對接的每單一條電線，可能無法承受大於 **1牛頓** 的張力，因此電線所處位置應謹慎妥善的配置。連接器周圍應具備足夠空間可供電線作適當彎折，以避免其產生張力承載於連接器

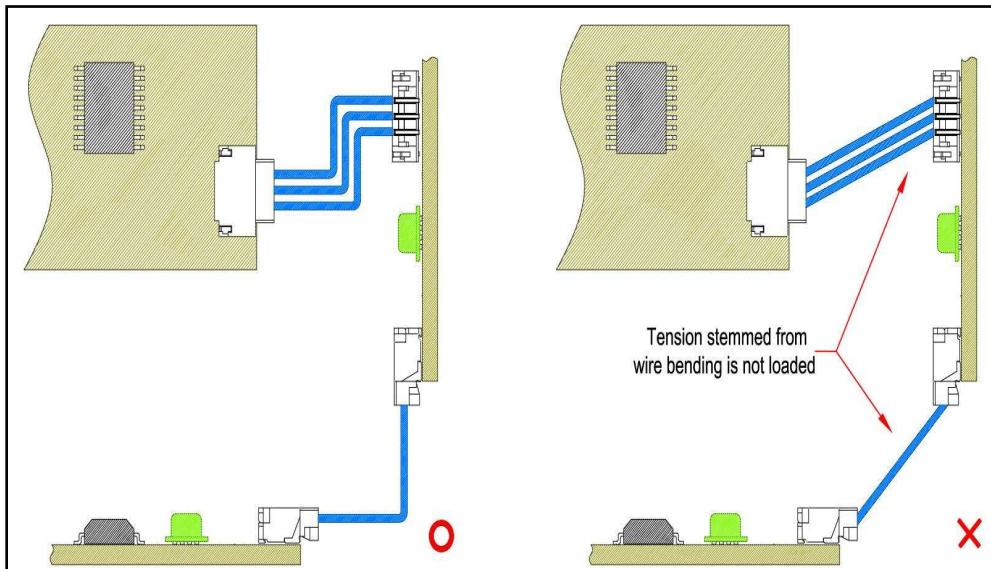


figure 6.1

Reviewed: J.M.Chang Approved: Peter Chang Verified: Indiana Huang